

Reference Conditions for Drying Mounted or Unmounted SMD Packages that were exposed to Conditions $\leq 60\%$ RH
 (For ICs with Novolac, Biphenyl and Multifunctional Epoxies)

Body Thickness	Level	Drying at 1% RH		Drying at 2% RH		Drying at 5% RH (according to IPC)	Bake, after exceeding floor life by >72 h (according to IPC)
		25°C 1% RH	40°C 1% RH	25°C 2% RH	40°C 2% RH	40°C 5% RH	90°C 5% RH
Thickness ≤ 1.4 mm	2a	2 days	1 day	5 days	2 days	5 days	23 hours
	3	3 days	1 day	8 days	3 days	8 days	33 hours
	4	4 days	2 days	9 days	4 days	9 days	37 hours
	5	5 days	2 days	10 days	5 days	10 days	41 hours
	5a	6 days	2 days	10 days	6 days	10 days	54 hours
	Thickness > 1.4 mm ≤ 2.0 mm	2a	10 days	3 days	22 days	10 days	22 days
3		11 days	3 days	23 days	11 days	23 days	4 days
4		14 days	4 days	28 days	14 days	28 days	5 days
5		16 days	5 days	35 days	16 days	35 days	6 days
5a		18 days	5 days	56 days	18 days	56 days	8 days
Thickness > 2.0 mm 4.5 mm	2a	20 days	6 days	67 days	20 days	67 days	10 days
	3	22 days	7 days	67 days	22 days	67 days	10 days
	4	22 days	7 days	67 days	22 days	67 days	10 days
	5	22 days	7 days	67 days	22 days	67 days	10 days
	5a	22 days	7 days	67 days	22 days	67 days	10 days